

WHAT IS CLAIMED IS:

1. A solder deposition method comprising the steps of:
providing a solder slab;
providing a complementary means having a plurality of
5 through holes;
providing a circuit element composed of an insulating body
and a plurality of conducting terminals embedded in the
insulating body, each of the conducting terminals having a
solder-retaining unit at one end; and
10 placing the circuit element under the complementary means
and the solder slab above the complementary means, injecting
a plurality of solder bits taken from the solder slab by a
punching device through the complementary means into the
solder-retaining units of the conducting terminals.
- 15 2. The solder deposition method according to claim 1, wherein a
step of punching a plurality of positioning holes on the solder
slab is further included, and one end of the conducting
terminals is pin-like and is for fitting into a positioning hole.
3. The solder deposition method according to claim 2, wherein
20 the positioning holes are formed by a first punching means,
and a plurality of solder bits are taken from the solder slab by
a second punching means.
4. The solder deposition method according to claim 2, wherein
the positioning holes are formed on the solder slab and a
25 plurality of solder bits are taken from the solder slab by a third
punching means; the third punching means is provided with a

first punch pin set and a second punch pin set for completing the positioning hole formation and the solder bit departure simultaneously.

- 5 5. The solder deposition method according to claim 4, wherein the complementary means has a section of first through holes and a section of second through holes, respectively corresponding to the first punch pin set and the second punch pin set.
- 10 6. The solder deposition method according to claim 1, wherein one end of each of the conducting terminals is a solder joint having a solder retaining unit for mounting a solder bit.
7. The solder deposition method according to claim 6, wherein the solder retaining units are a hole provided at each of the solder joints of the conducting terminals.
- 15 8. The solder deposition method according to claim 6, wherein holes are formed on the insulating body adjacent to the solder joints of the conducting terminals, and the solder retaining units are cavities defined by the holes and the solder joints.
9. The solder deposition method according to claim 6, wherein
20 the solder retaining units are holes formed on the insulating body close to the solder joints of the conducting terminals.
10. The solder deposition method according to claim 6, wherein the solder retaining units are solder binder applied to each of the top surface of the solder joints for adhesively mounting a
25 solder bit.
11. The solder deposition method according to claim 6, wherein the solder retaining units are sharp tips of the solder joints of

the conducting terminals and corresponding positioning holes of the solder bits; the solder bits are rivet mounted onto the solder joints through inserting the sharp tips into the positioning holes.